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UNRL110/111/113/114/115

Silicon PNP epitaxial planer type

For digital circuit

■ Features

- Mold leadless type package, allowing downsizing and thinning of the equipment and automatic insertion through the tape packing.
- The PCB mounting area is 1/10 of that of lead type package (3-pin MINI-type package).

■ Resistance by Part Number

	Marking Symbol	(R_1)	(R_2)
• UNRL110	P	$47~\mathrm{k}\Omega$	7 /
• UNRL111	A	10 kΩ	10 kΩ
• UNRL113	В	$47 \text{ k}\Omega$	$47 \text{ k}\Omega$
• UNRL114	R	$10 \text{ k}\Omega$	$47~\mathrm{k}\Omega$
• UNRL115	M	10 kΩ	

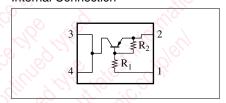
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector to base voltage	V_{CBO}	-50	V.	
Collector to emitter voltage	V_{CEO}	-50	V	
Collector current	I_{C}	-100	mA (
Total power dissipation *	P _T	150	mW	
Junction temperature	T _j	125	°C	
Storage temperature	$T_{\rm stg}$	-55 to +125	°C	

Note) *: Printed circuit board copper foil for collector portion area: 20.0 mm² or more, thickness: 1.6 mm

Unit: mm 3 4 1.00±0.05 1: Base 2: Emitter 3: Collector 4: Collector ML4-N1 Package

Internal Connection



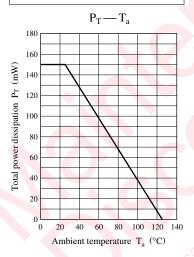
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

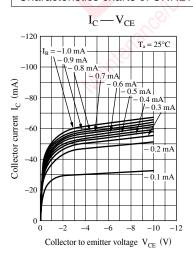
Par	ameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector cutofi	current	I_{CBO}	$V_{CB} = -50 \text{ V}, I_{E} = 0$			- 0.1	μΑ
	Mille	I_{CEO}	$V_{CE} = -50 \text{ V}, I_B = 0$			- 0.5	
Emitter cutoff	UNRL111	I_{EBO}	$V_{EB} = -6 \text{ V}, I_C = 0$			- 0.5	mA
current	UNRL114		Jegs Hill			- 0.2	
	UNRL113		X.			- 0.1	
	UNRL110/115					- 0.01	
Collector to bas	se voltage	V _{CBO}	$I_C = -10 \ \mu A, I_E = 0$	-50			V
Collector to em	itter voltage	V_{CEO}	$I_C = -2 \text{ mA}, I_B = 0$	-50			V
Forward current transfer ratio	UNRL111	h_{FE}	$V_{CE} = -10 \text{ V}, I_{C} = -5 \text{ mA}$	35			
	UNRL113/114			80			
	UNRL110/115			160		460	
Collector to emit	ter saturation voltage	V _{CE(sat)}	$I_C = -10 \text{ mA}, I_B = -0.3 \text{ mA}$			- 0.25	V

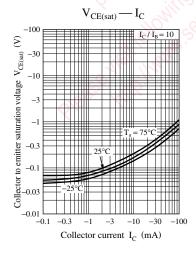
■ Electrical Characteristics(continued) $T_a = 25$ °C ± 3 °C

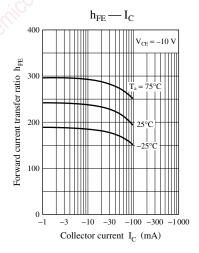
Par	ameter	Symbol	Conditions	Min	Тур	Max	Unit
High-level outp	ut voltage	V _{OH}	$V_{CC} = -5 \text{ V}, V_B = -0.5 \text{ V}, R_L = 1 \text{ k}\Omega$	-4.9			V
Low-level outp	ut voltage	V _{OL}	$V_{CC} = -5 \text{ V}, V_B = -2.5 \text{ V}, R_L = 1 \text{ k}\Omega$			- 0.2	V
	UNRL113		$V_{CC} = -5 \text{ V}, V_B = -3.5 \text{ V}, R_L = 1 \text{ k}\Omega$				
Transition frequ	iency	f_T	$V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$		80		MHz
Input resistance	UNRL111/114/115	R ₁		-30%	10	+30%	kΩ
	UNRL110/113				47		
Resistance ratio	UNRL111/113	R ₁ /R ₂		0.8	1.0	1.2	
	UNRL114			0.17	0.21	0.25	

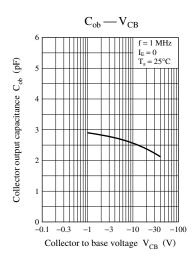
Common characteristics chart

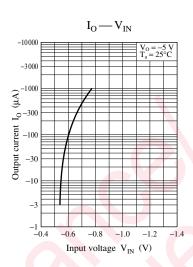


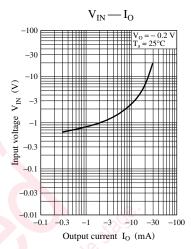


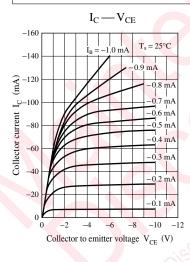


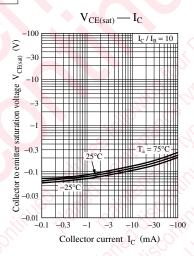


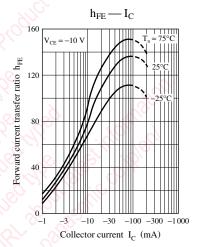


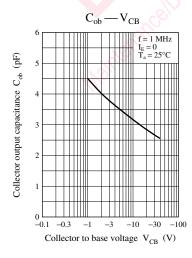


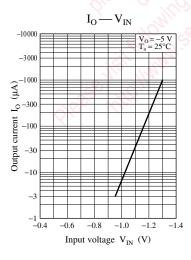


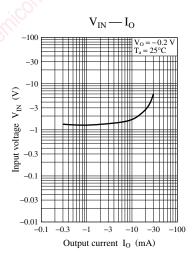




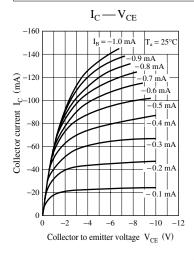


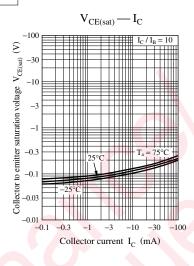


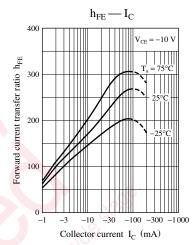


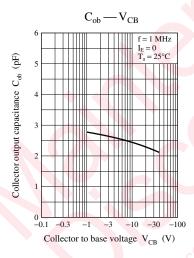


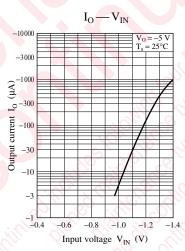
Characteristics charts of UNRL113

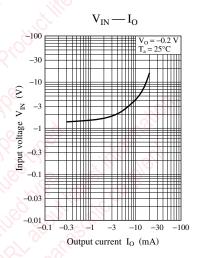


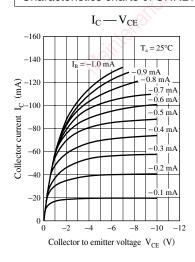


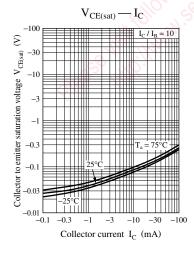


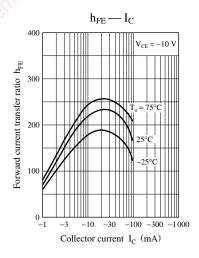


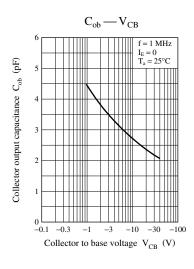


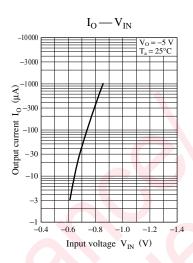


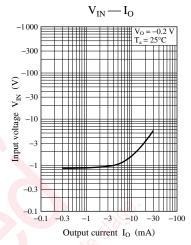


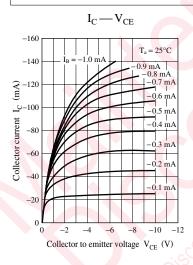


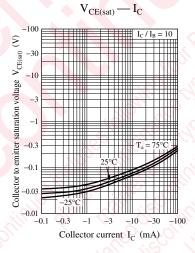


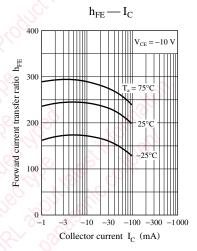


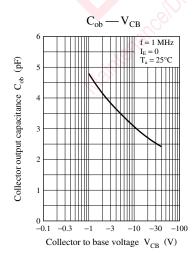


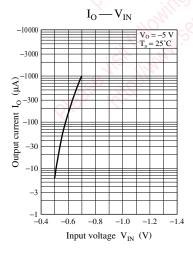


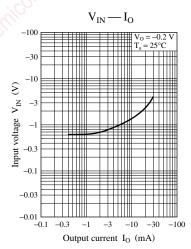












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